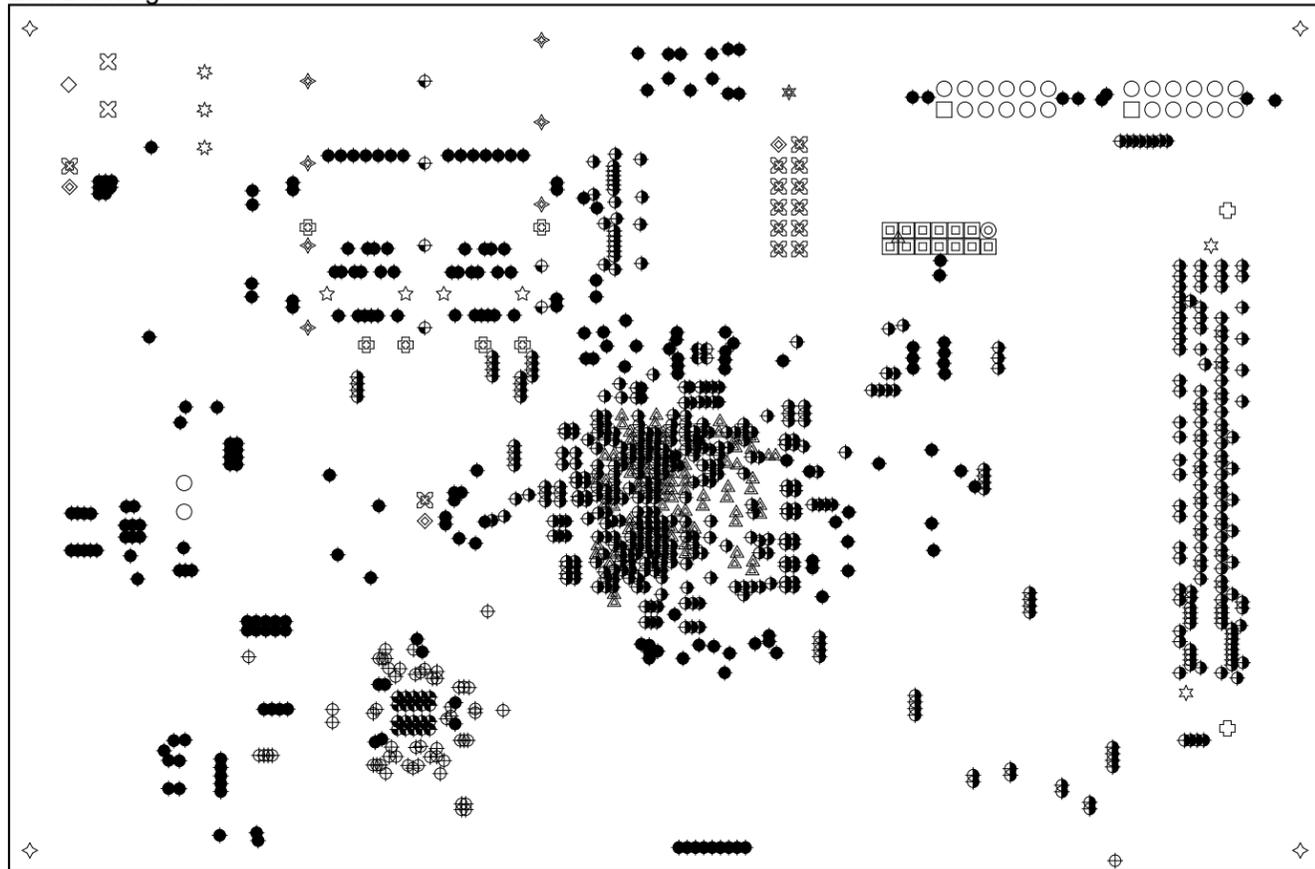


Drill Drawing View



Notes:

- 1. Via template v41h20m0mx0 is an in-pad, tented, ink filled via.
- 2. Via template Via1 is a tented, ink filled via.
- 3. Pads with templates r165_406h100_310 and r165_406h100_318 are slots with a 1mm hole size and 3.1mm length.

Drill Table

Symbol	Count	Hole Size	Plated	Hole Type	Via / Pad	Template
□	2	0.76mm(30.00mil)	Plated	Round	Pad	s152h76
○	24	0.76mm(30.00mil)	Plated	Round	Pad	c152h76
◇	1	1.00mm(39.37mil)	Plated	Slot	Pad	r165_406h100_310
⊗	2	1.00mm(39.37mil)	Plated	Slot	Pad	r165_406h100_318
⊕	2	2.70mm(106.30mil)	Plated	Round	Pad	c320h270
◇	4	3.00mm(118.11mil)	Plated	Round	Pad	c400h300
☆	4	1.55mm(61.02mil)	Plated	Round	Pad	c155h155m155p155
☆	2	1.27mm(50.00mil)	Non-Plated	Round	Pad	c0hn127
☆	3	1.85mm(72.83mil)	Plated	Round	Pad	c270h185
△	1	1.00mm(39.37mil)	Plated	Round	Pad	c100h100
⊠	13	0.90mm(35.43mil)	Plated	Round	Pad	c130h90(Tol5-5)
⊙	1	0.90mm(35.43mil)	Plated	Round	Pad	s130h90c50(Tol5-5)
◇	3	0.90mm(35.43mil)	Plated	Round	Pad	s150h90
⊗	13	0.90mm(35.43mil)	Plated	Round	Pad	c150h90
⊕	6	0.95mm(37.40mil)	Plated	Round	Pad	c95h95
◇	7	1.05mm(41.34mil)	Plated	Round	Pad	s200h105m0
⊕	6	0.95mm(37.40mil)	Plated	Round	Pad	s200h95m0
☆	1	3.20mm(125.98mil)	Plated	Round	Pad	c500h320
⊕	524	0.20mm(8.00mil)	Plated	Round	Via	Via1
△	72	0.20mm(8.00mil)	Plated	Round	Via	v41h20m0mx0
●	243	0.25mm(10.00mil)	Plated	Round	Via	v51h25
⊕	58	0.18mm(7.00mil)	Plated	Round	Via	v38h18
⊕	20	0.25mm(10.00mil)	Plated	Round	Via	v64h25
⊕	4	0.20mm(7.87mil)	Plated	Round	Via	v50h20

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		UNLESS OTHERWISE SPECIFIED:		NAME	DATE	University College London	
		DIMENSIONS ARE IN INCHES		DRAWN	Samer Kilani	21/7/2017	TITLE ATFC Master Drawing
		TOLERANCES:		CHECKED			
		FRACTIONAL±		ENG APPR.			
		ANGULAR: MACH± BEND ±		MFG APPR.			
		TWO PLACE DECIMAL ±		Q.A.			SIZE
		THREE PLACE DECIMAL ±		COMMENTS:			
		INTERPRET GEOMETRIC TOLERANCING PER:					SCALE: 1:1
		MATERIAL					WEIGHT:
NEXT ASSY	USED ON	FINISH					SHEET 1 OF 4
APPLICATION		DO NOT SCALE DRAWING					

A

B

C

D

Layer Stack Legend

Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Top Paste			Paste Mask	GTP
	Top Overlay			Legend	GTO
Surface Material	Top Solder	0.025mm(0.984mil)	Solder Resist	Solder Mask	GTS
Copper	Component Side	0.035mm(1.378mil)		Signal	GTL
Prepreg		0.115mm(4.528mil)		Dielectric	
Copper	Ground Plane (GND)	0.035mm(1.378mil)		Internal Plane	GP1
Core		0.400mm(15.748mil)		Dielectric	
Copper	GND/Signal	0.035mm(1.378mil)		Signal	G1
Prepreg		0.296mm(11.654mil)		Dielectric	
Copper	VCCO/Signal	0.035mm(1.378mil)		Signal	G2
Core		0.400mm(15.748mil)		Dielectric	
Copper	VCCINT/VCCAUX	0.035mm(1.378mil)		Internal Plane	GP2
Prepreg		0.115mm(4.528mil)		Dielectric	
Copper	Bottom Side	0.035mm(1.378mil)		Signal	GBL
Surface Material	Bottom Solder	0.025mm(0.984mil)	Solder Resist	Solder Mask	GBS
	Bottom Overlay			Legend	GBO
	Bottom Paste			Paste Mask	GBP

Total thickness: 1.586mm(62.440mil)

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		DIMENSIONS ARE IN INCHES	DRAWN	Samer Kilani	21/7/2017	TITLE ATFC Master Drawing
		TOLERANCES:	CHECKED			
		FRACTIONAL ±	ENG APPR.			
		ANGULAR: MACH ± BEND ±	MFG APPR.			
		TWO PLACE DECIMAL ±	Q.A.			
		THREE PLACE DECIMAL ±	COMMENTS:			SIZE
		INTERPRET GEOMETRIC TOLERANCING PER:				DWG. NO.
		MATERIAL				
		FINISH				
NEXT ASSY	USED ON	DO NOT SCALE DRAWING				
APPLICATION						SCALE: 1:1
						WEIGHT:
						SHEET 2 OF 4

A

B

C

D

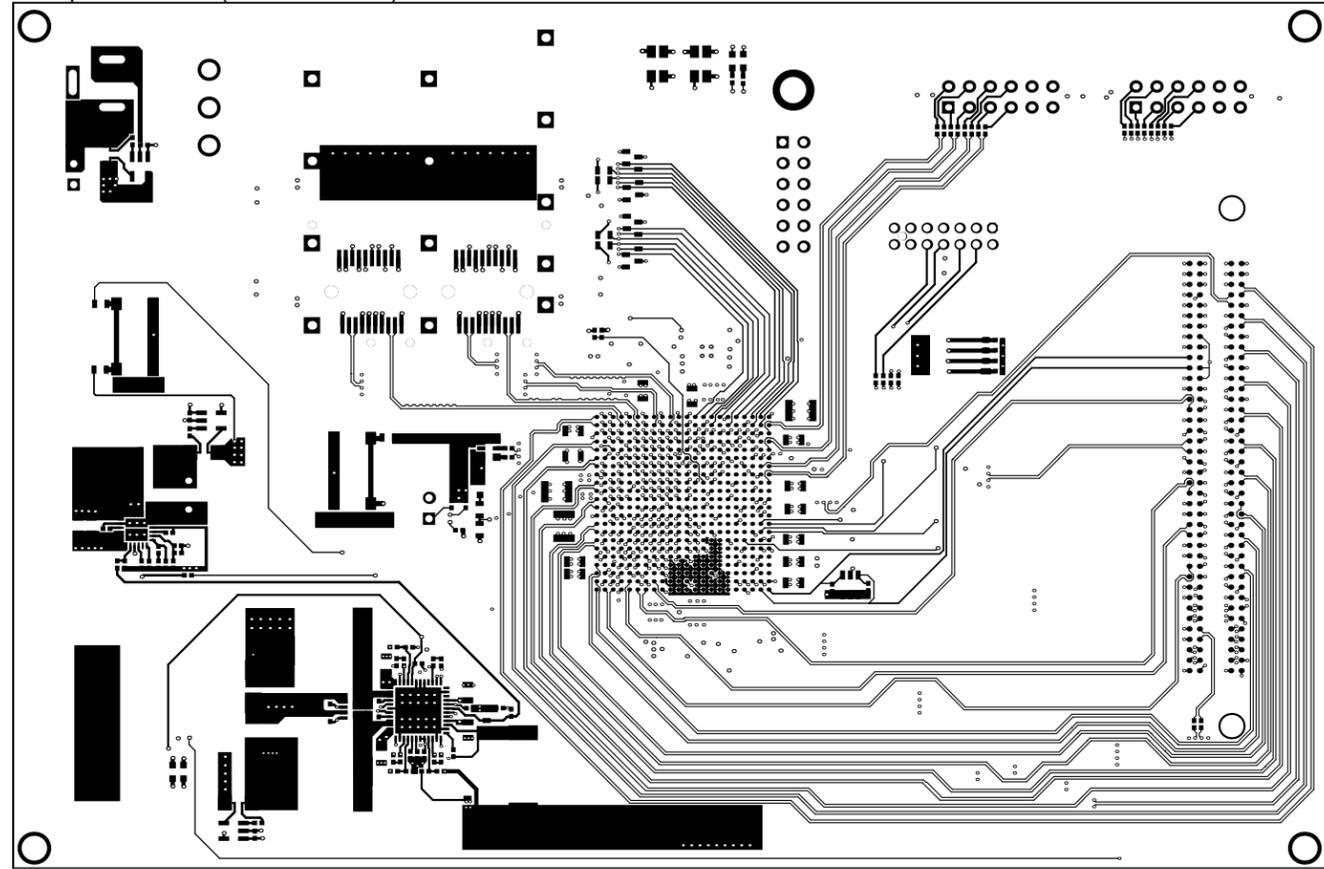
A

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Component Side (Scale: 1.1392)



1

1

2

2

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		UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN INCHES TOLERANCES: FRACTIONAL ± ANGULAR: MACH ± BEND ± TWO PLACE DECIMAL ± THREE PLACE DECIMAL ± INTERPRET GEOMETRIC TOLERANCING PER: MATERIAL	NAME	DATE	University College London	
			DRAWN	Samer Kilani	21/7/2017	TITLE
			CHECKED		ATFC Master Drawing	
			ENG APPR.		SIZE	
			MFG APPR.		DWG. NO.	
			Q.A.		SCALE: 1:1	
			COMMENTS:		WEIGHT:	
NEXT ASSY	USED ON	FINISH			SHEET 3 OF 4	
APPLICATION		DO NOT SCALE DRAWING				

A

B

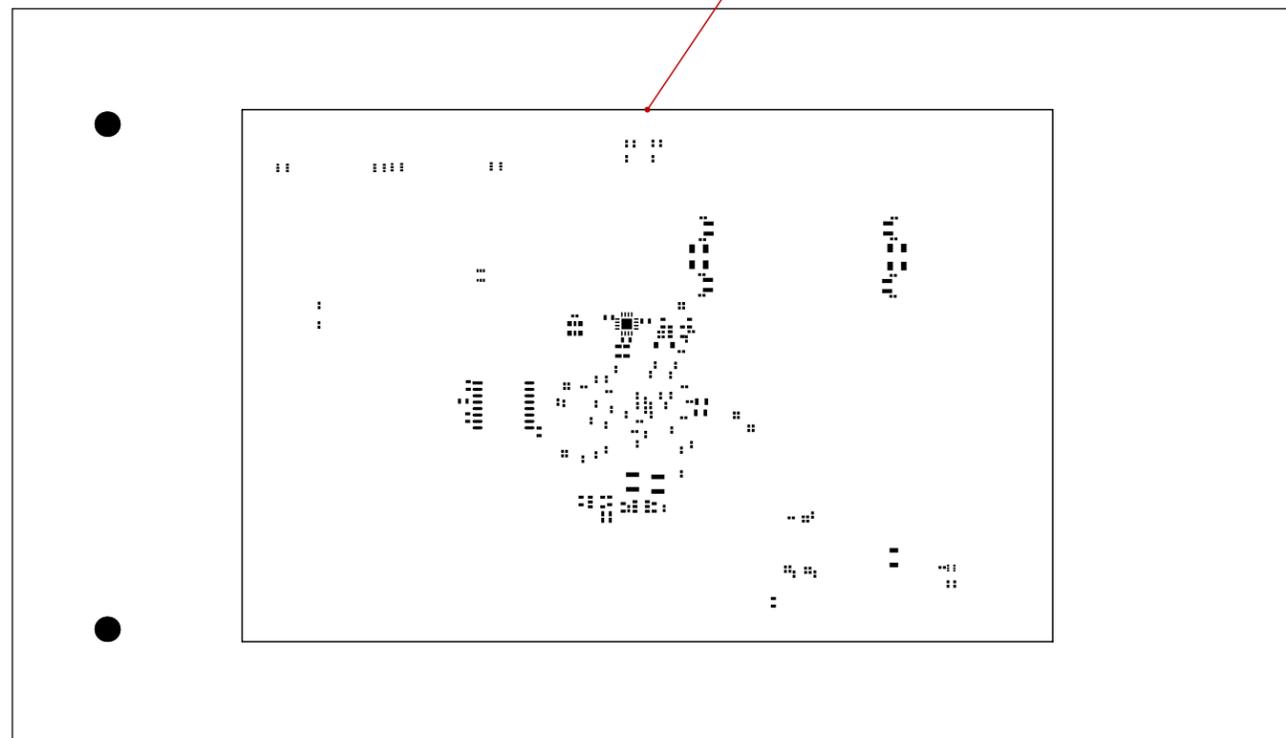
C

D

Notes:

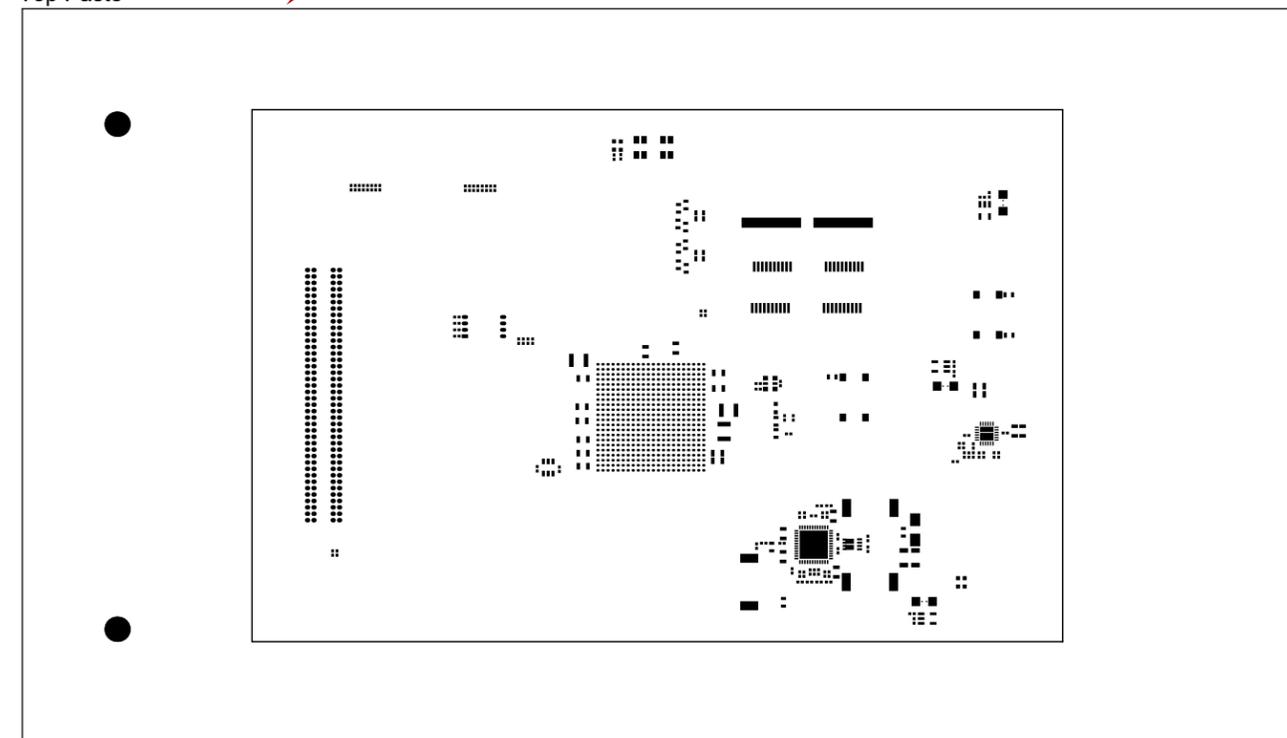
- 4. Diagrams below are scaled down to 70%.
- 5. Top and Bottom stencil files are in seperate gerber files. atfc_paste_bot.gbr and atfc_paste_top.gbr, respectively.
- 6. Paste and Pad sizes are 1:1. Please scale down paste pads to achieve better paste deposition.
- 7. DO NOT scale down the 5mm holes on the LHS of the stencils. These are mounting holes for the stencil printer.

Bottom Paste



Board layout not included
in the stencil gerber file.

Top Paste



Stencil border

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		DIMENSIONS ARE IN INCHES		DRAWN	Samer Kilani	21/7/2017	TITLE ATFC Master Drawing		
		TOLERANCES:		CHECKED					
		FRACTIONAL ±		ENG APPR.					
		ANGULAR: MACH ± BEND ±		MFG APPR.					
		TWO PLACE DECIMAL ±		Q.A.			SIZE	DWG. NO.	
		THREE PLACE DECIMAL ±		COMMENTS:					
		INTERPRET GEOMETRIC TOLERANCING PER:		Stencil design					
		MATERIAL							
		FINISH							
NEXT ASSY	USED ON	APPLICATION	DO NOT SCALE DRAWING				SCALE: 1:1	WEIGHT:	SHEET 4 OF 4